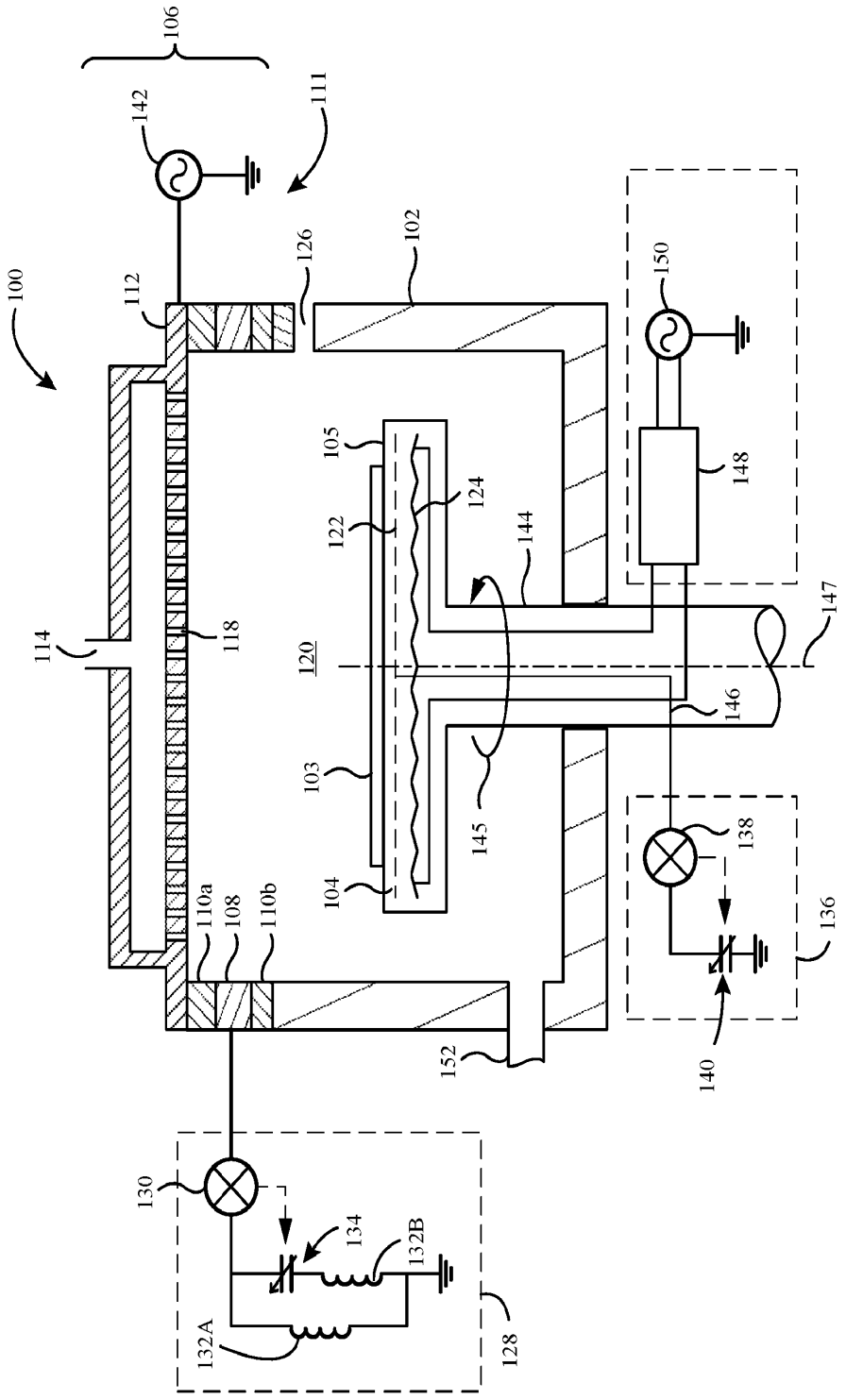
106
142
111
126
102
100
112
150
105
124
148
122
144
147
114
118
120
146
103
145
138
104
110a
108
110b
136
152
140
130
134
132B
132A
128

FIG. 1

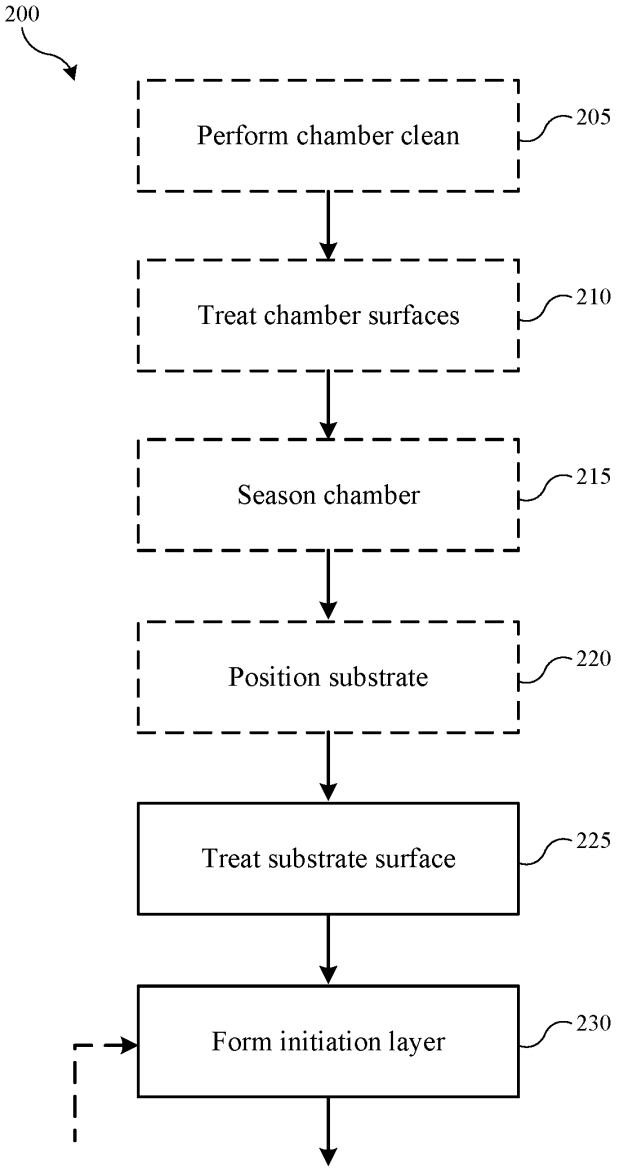
200
Perform chamber clean
205
Treat chamber surfaces
210
Season chamber
215
Position substrate
220
Treat substrate surface
225
Form initiation layer
230

FIG. 2A

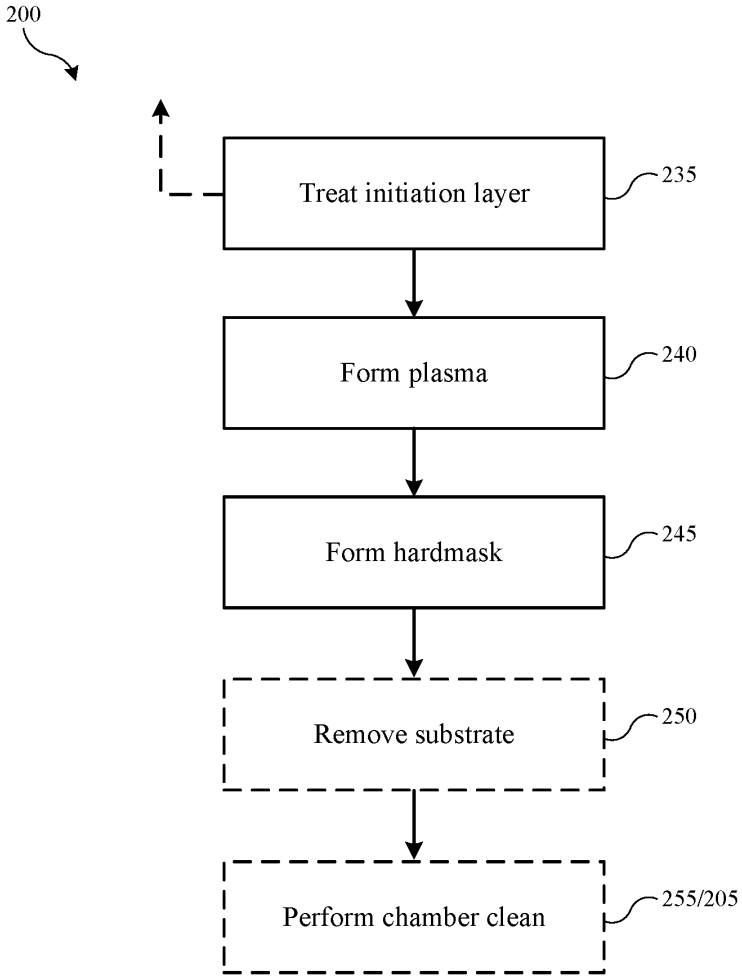
200
Treat initiation layer
235
Form plasma
240
Form hardmask
245
Remove substrate
250
Perform chamber clean
255/205

FIG. 2B